

## High voltage ultrafast rectifier

### Main product characteristics

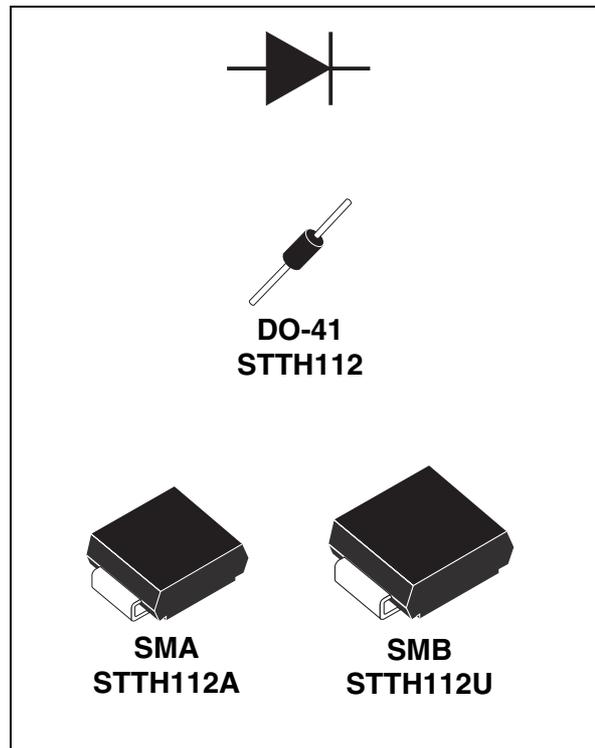
$I_{F(AV)}$	1 A
$V_{RRM}$	1200 V
$T_j(max)$	175° C
$V_F(max)$	1.65 V

### Features and benefits

- Low forward voltage drop
- High reliability
- High surge current capability
- Soft switching for reduced EMI disturbances
- Planar technology

### Description

The STTH112, which is using ST ultrafast high voltage planar technology, is specially suited for free-wheeling, clamping, snubbing, demagnetization in power supplies and other power switching applications



**Table 1. Absolute ratings (limiting values)**

Symbol	Parameter			Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage			1200	V
$V_{(RMS)}$	RMS voltage			850	V
$I_{F(AV)}$	Average forward current	$T_I = 85^\circ\text{C}$ $\delta = 0.5$	DO-41	1	A
		$T_I = 115^\circ\text{C}$ $\delta = 0.5$	SMA		
		$T_I = 125^\circ\text{C}$ $\delta = 0.5$	SMB		
$I_{FSM}$	Forward surge current $t = 8.3\text{ ms}$	DO-41		20	A
		SMA		18	
		SMB			
$T_{stg}$	Storage temperature range			- 50 + 175	°C
$T_j$	Maximum operating junction temperature			+ 175	°C

# 1 Electrical characteristics

**Table 2. Thermal parameters**

Symbol	Parameter			Value	Unit
$R_{th(j-l)}$	Junction to lead	L = 10 mm	DO-41	45	°C/W
			SMA	30	
			SMB	25	
$R_{th(j-a)}$	Junction to ambient	L = 10 mm	DO-41	110	

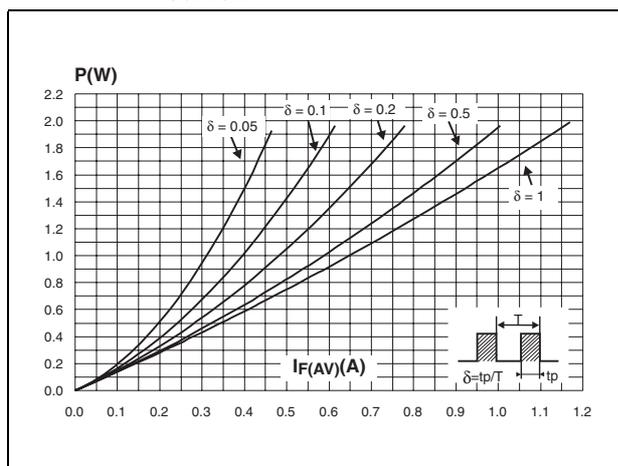
**Table 3. Static electrical characteristics**

Symbol	Parameter	Tests conditions	Min.	Typ.	Max.	Unit
$I_R$	Reverse leakage current	$V_R = 1200V$	$T_j = 25^\circ C$		5	$\mu A$
			$T_j = 125^\circ C$		50	
$V_F$	Forward voltage drop	$I_F = 1 A$	$T_j = 25^\circ C$		1.9	V
			$T_j = 125^\circ C$		1.17	
			$T_j = 150^\circ C$		1.10	

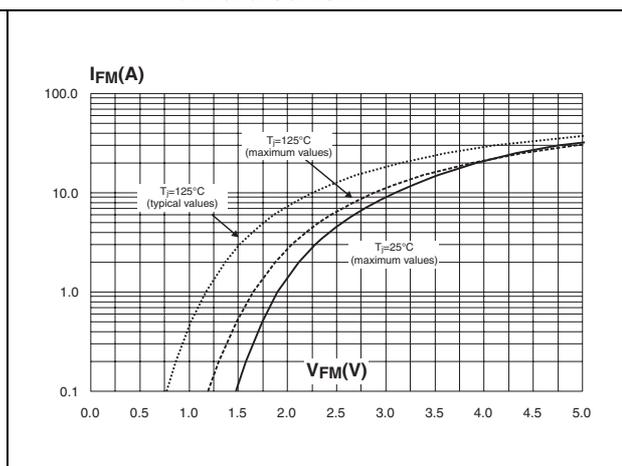
**Table 4. Dynamic electrical characteristics**

Symbol	Parameter	Tests conditions	Min.	Typ.	Max.	Unit
$t_{rr}$	Reverse recovery time	$I_F = 0.5 A$ $I_{rr} = 0.25 A$ $I_R = 1 A$	$T_j = 25^\circ C$		75	ns
$t_{fr}$	Forward recovery time	$I_F = 1 A$ $di_F/dt = 50 A/\mu s$ $V_{FR} = 1.1 \times V_{Fmax}$	$T_j = 25^\circ C$		500	ns
$V_{FP}$	Forward recovery voltage				30	V

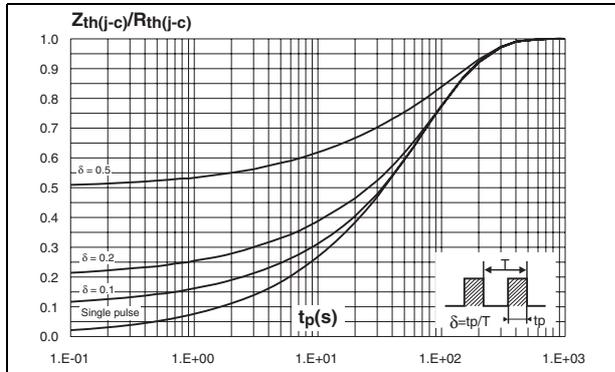
**Figure 1. Conduction losses versus average current**



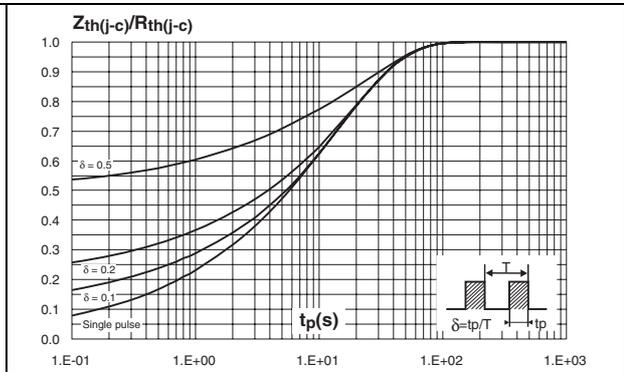
**Figure 2. Forward voltage drop versus forward current.**



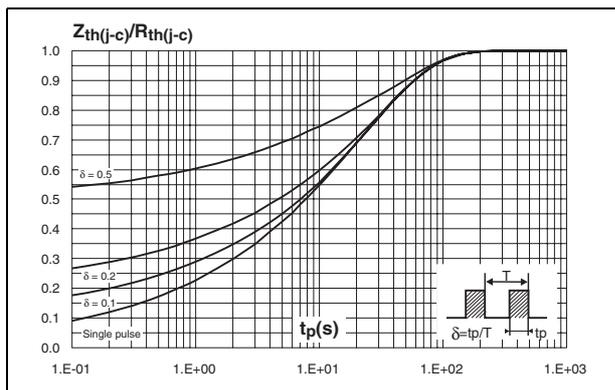
**Figure 3. Relative variation of thermal impedance junction ambient versus pulse duration (epoxy FR4,  $L_{leads} = 10\text{mm}$ ) (DO-41).**



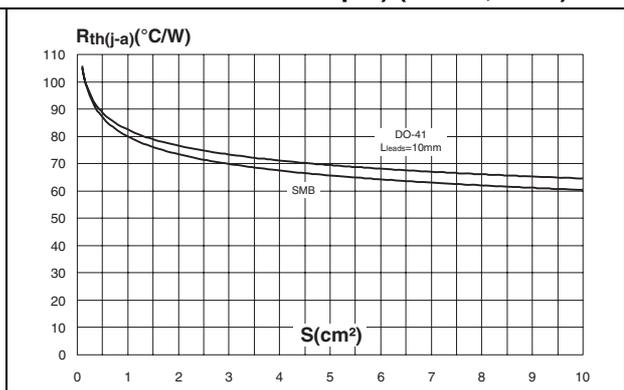
**Figure 4. Relative variation of thermal impedance junction ambient versus pulse duration (epoxy FR4) (SMA).**



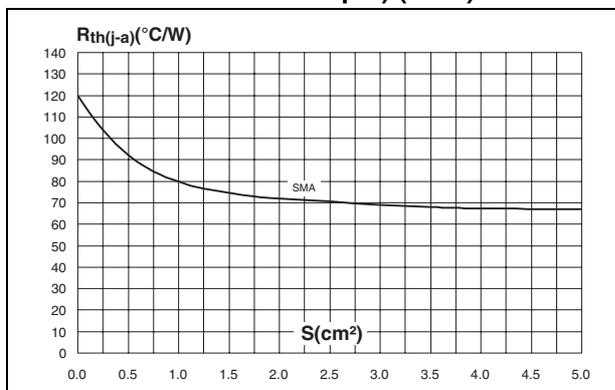
**Figure 5. Relative variation of thermal impedance junction ambient versus pulse duration (epoxy FR4)(SMB).**



**Figure 6. Thermal resistance junction to ambient versus copper surface under each lead (epoxy printed circuit board FR4, copper thickness:  $35\ \mu\text{m}$ ) (DO-41, SMB).**



**Figure 7. Thermal resistance junction to ambient versus copper surface under each lead (epoxy printed circuit board FR4, copper thickness:  $35\ \mu\text{m}$ ) (SMA).**



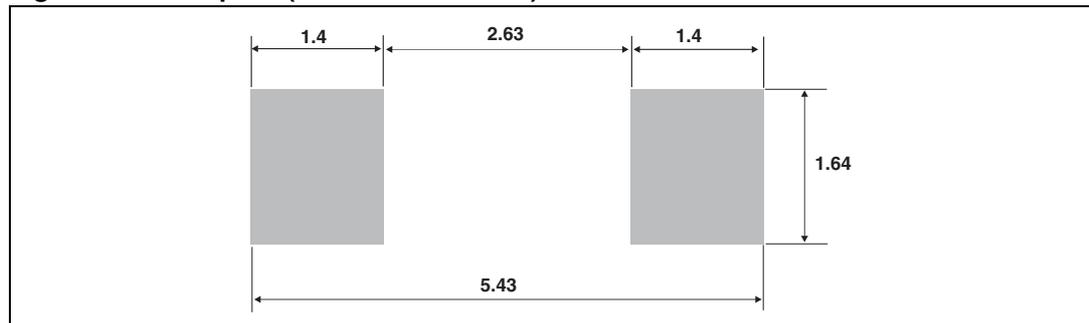
## 2 Package mechanical data

- Epoxy meets UL 94, V0

**Table 5. SMA dimensions**

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.094
A2	0.05	0.20	0.002	0.008
b	1.25	1.65	0.049	0.065
c	0.15	0.40	0.006	0.016
D	2.25	2.90	0.089	0.114
E	4.80	5.35	0.189	0.211
E1	3.95	4.60	0.156	0.181
L	0.75	1.50	0.030	0.059

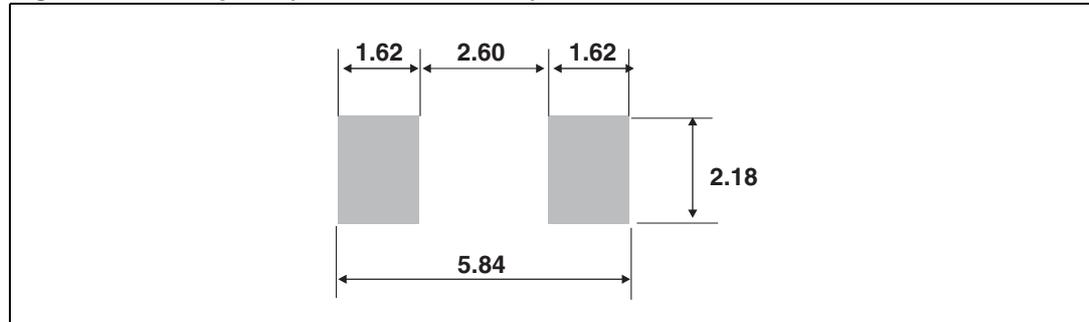
**Figure 8. Footprint (dimensions in mm)**



**Table 6. SMB dimensions**

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.096
A2	0.05	0.20	0.002	0.008
b	1.95	2.20	0.077	0.087
c	0.15	0.40	0.006	0.016
D	3.30	3.95	0.130	0.156
E	5.10	5.60	0.201	0.220
E1	4.05	4.60	0.159	0.181
L	0.75	1.50	0.030	0.059

**Figure 9. Footprint (dimensions in mm)**



**Table 7. DO-41 dimensions**

REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.07	5.20	0.160	0.205
B	2.04	2.71	0.080	0.107
C	28		1.102	
D	0.712	0.863	0.028	0.034

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: [www.st.com](http://www.st.com).

### 3 Ordering information

Ordering code	Marking	Package	Weight	Base qty	Delivery Mode
STTH112	STTH112	DO-41	0.34 g	2000	Ammopack
STTH112A	H12	SMA	0.068 g	5000	Tape and reel
STTH112U	U12	SMB	0.11 g	2500	Tape and reel
STTH112RL	STTH112	DO-41	0.34 g	5000	Tape and reel

### 4 Revision history

Date	Revision	Changes
Jan-2003	2	Initial release.
22-Jun-2005	3	New value of $T_j = 150^\circ\text{C}$ added to table 2. Dimensions A1 E and D updated in Table 4. Data sheet reformatted. No other technical changes
20-Mar-2007	4	Reformatted to current standards. Updated dimensions and footprints for SMA and SMB packages.

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